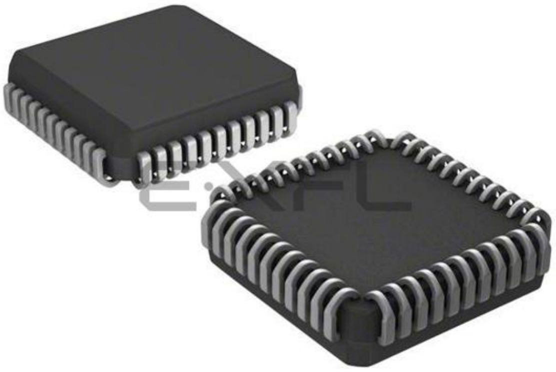

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf874-04i-l

TABLE 2-1: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Details on page:
Bank 1											
80h(3)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	27
81h	OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	19
82h(3)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	26
83h(3)	STATUS	IRP	RP1	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	18
84h(3)	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	27
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	29
86h	TRISB	PORTB Data Direction Register								1111 1111	31
87h	TRISC	PORTC Data Direction Register								1111 1111	33
88h(4)	TRISD	PORTD Data Direction Register								1111 1111	35
89h(4)	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits			0000 -111	37
8Ah(1,3)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	26
8Bh(3)	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	20
8Ch	PIE1	PSPIE(2)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	21
8Dh	PIE2	—	(5)	—	EEIE	BCLIE	—	—	CCP2IE	-r-0 0--0	23
8Eh	PCON	—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	---- --qq	25
8Fh	—	Unimplemented								—	—
90h	—	Unimplemented								—	—
91h	SSPCON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000	68
92h	PR2	Timer2 Period Register								1111 1111	55
93h	SSPADD	Synchronous Serial Port (I^2C mode) Address Register								0000 0000	73, 74
94h	SSPSTAT	SMP	CKE	D/$\overline{\text{A}}$	P	S	R/$\overline{\text{W}}$	UA	BF	0000 0000	66
95h	—	Unimplemented								—	—
96h	—	Unimplemented								—	—
97h	—	Unimplemented								—	—
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	95
99h	SPBRG	Baud Rate Generator Register								0000 0000	97
9Ah	—	Unimplemented								—	—
9Bh	—	Unimplemented								—	—
9Ch	—	Unimplemented								—	—
9Dh	—	Unimplemented								—	—
9Eh	ADRESL	A/D Result Register Low Byte								xxxx xxxx	116
9Fh	ADCON1	ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0	0--- 0000	112

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved.
Shaded locations are unimplemented, read as ‘0’.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.
2: Bits PSPIE and PSPIF are reserved on PIC16F873/876 devices; always maintain these bits clear.
3: These registers can be addressed from any bank.
4: PORTD, PORTE, TRISD, and TRISE are not physically implemented on PIC16F873/876 devices; read as ‘0’.
5: PIR2<6> and PIE2<6> are reserved on these devices; always maintain these bits clear.

3.3 PORTC and the TRISC Register

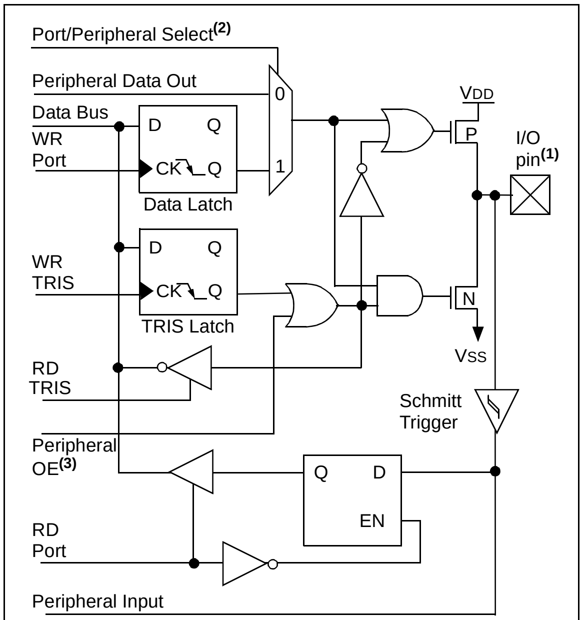
PORTC is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISC. Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., put the contents of the output latch on the selected pin).

PORTC is multiplexed with several peripheral functions (Table 3-5). PORTC pins have Schmitt Trigger input buffers.

When the I^2C module is enabled, the PORTC<4:3> pins can be configured with normal I^2C levels, or with SMBus levels by using the CKE bit (SSPSTAT<6>).

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (`BSF, BCF, XORWF`) with TRISC as destination, should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

FIGURE 3-5: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE) RC<2:0>, RC<7:5>

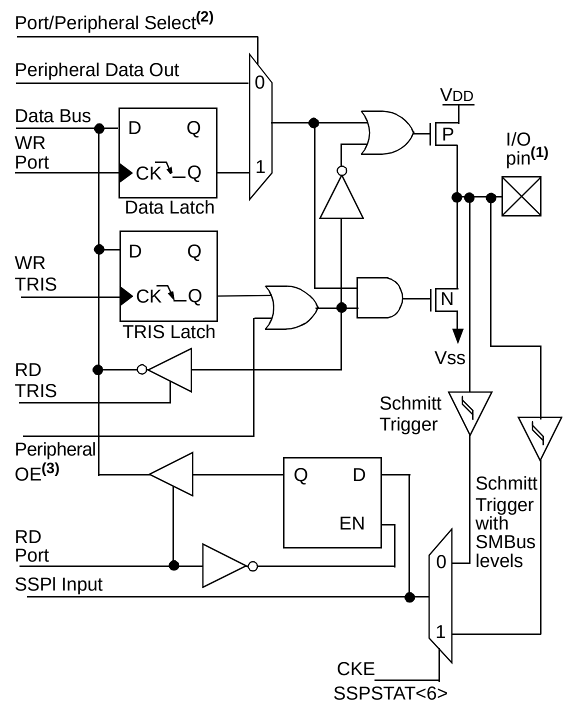


Note 1: I/O pins have diode protection to VDD and VSS.

2: Port/Peripheral select signal selects between port data and peripheral output.

3: Peripheral OE (output enable) is only activated if peripheral select is active.

FIGURE 3-6: PORTC BLOCK DIAGRAM (PERIPHERAL OUTPUT OVERRIDE) RC<4:3>



Note 1: I/O pins have diode protection to VDD and VSS.

2: Port/Peripheral select signal selects between port data and peripheral output.

3: Peripheral OE (output enable) is only activated if peripheral select is active.

REGISTER 3-1: TRISE REGISTER (ADDRESS 89h)

R-0	R-0	R/W-0	R/W-0	U-0	R/W-1	R/W-1	R/W-1
IBF	OBF	IBOV	PSPMODE	—	Bit2	Bit1	Bit0
bit 7							bit 0

Parallel Slave Port Status/Control Bits:

bit 7 **IBF:** Input Buffer Full Status bit
1 = A word has been received and is waiting to be read by the CPU
0 = No word has been received

bit 6 **OBF**: Output Buffer Full Status bit
1 = The output buffer still holds a previously written word
0 = The output buffer has been read

bit 5 **IBOV**: Input Buffer Overflow Detect bit (in Microprocessor mode)
1 = A write occurred when a previously input word has not been read (must be cleared in software)
0 = No overflow occurred

bit 4 **PSPMODE**: Parallel Slave Port Mode Select bit
1 = PORTD functions in Parallel Slave Port mode
0 = PORTD functions in general purpose I/O mode

bit 3 **Unimplemented**: Read as '0'

PORTE Data Direction Bits:

bit 2 **Bit2**: Direction Control bit for pin RE2/$\overline{CS}$/AN7
1 = Input
0 = Output

bit 1 **Bit1**: Direction Control bit for pin RE1/$\overline{WR}$/AN6
1 = Input
0 = Output

bit 0 **Bit0**: Direction Control bit for pin RE0/$\overline{RD}$/AN5
1 = Input
0 = Output

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

NOTES:

11.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has five inputs for the 28-pin devices and eight for the other devices.

The analog input charges a sample and hold capacitor. The output of the sample and hold capacitor is the input into the converter. The converter then generates a digital result of this analog level via successive approximation. The A/D conversion of the analog input signal results in a corresponding 10-bit digital number. The A/D module has high and low voltage reference input that is software selectable to some combination of V_{DD}, V_{SS}, RA2, or RA3.

The A/D converter has a unique feature of being able to operate while the device is in SLEEP mode. To operate in SLEEP, the A/D clock must be derived from the A/D's internal RC oscillator.

The A/D module has four registers. These registers are:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register0 (ADCON0)
- A/D Control Register1 (ADCON1)

The ADCON0 register, shown in Register 11-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 11-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be the voltage reference), or as digital I/O.

Additional information on using the A/D module can be found in the PIC® MCU Mid-Range Family Reference Manual (DS33023).

REGISTER 11-1: ADCON0 REGISTER (ADDRESS: 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON
bit 7							bit 0

bit 7-6 **ADCS1:ADCS0:** A/D Conversion Clock Select bits
`00` = FOSC/2
`01` = FOSC/8
`10` = FOSC/32
`11` = FRC (clock derived from the internal A/D module RC oscillator)

bit 5-3 **CHS2:CHS0**: Analog Channel Select bits
`000` = channel 0, (RA0/AN0)
`001` = channel 1, (RA1/AN1)
`010` = channel 2, (RA2/AN2)
`011` = channel 3, (RA3/AN3)
`100` = channel 4, (RA5/AN4)
`101` = channel 5, (RE0/AN5)(1)
`110` = channel 6, (RE1/AN6)(1)
`111` = channel 7, (RE2/AN7)(1)

bit 2 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit
<u>If ADON = 1:</u>
`1` = A/D conversion in progress (setting this bit starts the A/D conversion)
`0` = A/D conversion not in progress (this bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1 **Unimplemented**: Read as '0'

bit 0 **ADON**: A/D On bit
`1` = A/D converter module is operating
`0` = A/D converter module is shut-off and consumes no operating current

Note 1: These channels are not available on PIC16F873/876 devices.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

11.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires a minimum 12TAD per 10-bit conversion. The source of the A/D conversion clock is software selected. The four possible options for TAD are:

- 2TOSC
- 8TOSC
- 32TOSC
- Internal A/D module RC oscillator (2-6 μs)

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 μs.

Table 11-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 11-1: TAD vs. MAXIMUM DEVICE OPERATING FREQUENCIES (STANDARD DEVICES (C))

AD Clock Source (TAD)		Maximum Device Frequency
Operation	**ADCS1:ADCS0**	**Max.**
2TOSC	00	1.25 MHz
8TOSC	01	5 MHz
32TOSC	10	20 MHz
RC[1, 2, 3]	11	**(Note 1)**

Note 1: The RC source has a typical TAD time of 4 μs, but can vary between 2-6 μs.
2: When the device frequencies are greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.
3: For extended voltage devices (LC), please refer to the Electrical Characteristics (Sections 15.1 and 15.2).

11.3 Configuring Analog Port Pins

The ADCON1 and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, any pin configured as an analog input channel will read as cleared (a low level). Pins configured as digital inputs will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

2: Analog levels on any pin that is defined as a digital input (including the AN7:AN0 pins), may cause the input buffer to consume current that is out of the device specifications.

12.2 Oscillator Configurations

12.2.1 OSCILLATOR TYPES

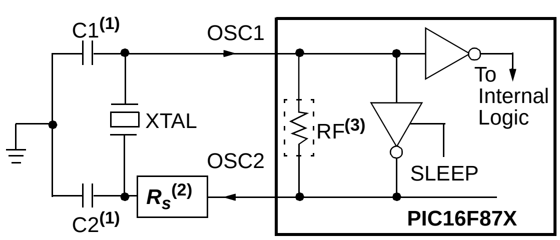
The PIC16F87X can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1 and FOSC0) to select one of these four modes:

- LP Low Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC Resistor/Capacitor

12.2.2 CRYSTAL OSCILLATOR/CERAMIC RESONATORS

In XT, LP or HS modes, a crystal or ceramic resonator is connected to the OSC1/CLKIN and OSC2/CLKOUT pins to establish oscillation (Figure 12-1). The PIC16F87X oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1/CLKIN pin (Figure 12-2).

FIGURE 12-1: CRYSTAL/CERAMIC RESONATOR OPERATION (HS, XT OR LP OSC CONFIGURATION)



Note 1: See Table 12-1 and Table 12-2 for recommended values of C1 and C2.

2: A series resistor (***R_S***) may be required for AT strip cut crystals.

3: RF varies with the crystal chosen.

FIGURE 12-2: EXTERNAL CLOCK INPUT OPERATION (HS, XT OR LP OSC CONFIGURATION)

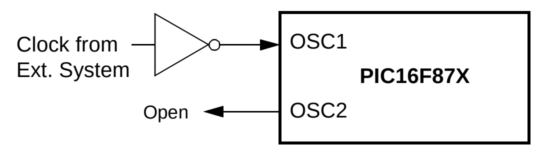


TABLE 12-1: CERAMIC RESONATORS

Ranges Tested:			
Mode	**Freq.**	**OSC1**	**OSC2**
XT	455 kHz 2.0 MHz 4.0 MHz	68 - 100 pF 15 - 68 pF 15 - 68 pF	68 - 100 pF 15 - 68 pF 15 - 68 pF
HS	8.0 MHz 16.0 MHz	10 - 68 pF 10 - 22 pF	10 - 68 pF 10 - 22 pF
These values are for design guidance only. See notes following Table 12-2.			
Resonators Used:			
455 kHz	Panasonic EFO-A455K04B		± 0.3%
2.0 MHz	Murata Erie CSA2.00MG		± 0.5%
4.0 MHz	Murata Erie CSA4.00MG		± 0.5%
8.0 MHz	Murata Erie CSA8.00MT		± 0.5%
16.0 MHz	Murata Erie CSA16.00MX		± 0.5%
All resonators used did not have built-in capacitors.			

12.10 Interrupts

The PIC16F87X family has up to 14 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit, or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all unmasked interrupts, or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set, regardless of the status of the GIE bit. The GIE bit is cleared on RESET.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine, as well as sets the GIE bit, which re-enables interrupts.

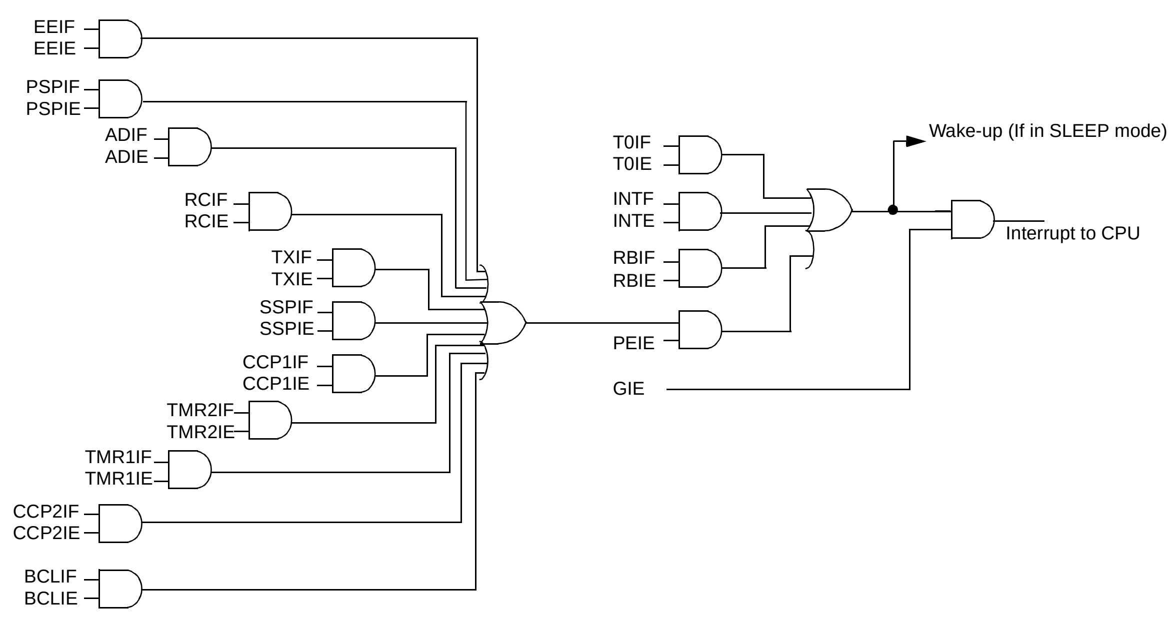
The RB0/INT pin interrupt, the RB port change interrupt, and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers, PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers, PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs. The latency is the same for one or two-cycle instructions. Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit, PEIE bit, or GIE bit.

FIGURE 12-9: INTERRUPT LOGIC



The following table shows which devices have which interrupts.

Device	T0IF	INTF	RBIF	PSPIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	EEIF	BCLIF	CCP2IF
PIC16F876/873	Yes	Yes	Yes	—	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16F877/874	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

CALL	Call Subroutine
Syntax:	[*label*] CALL k
Operands:	$0 \le k \le 2047$
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. `CALL` is a two-cycle instruction.

CLRF	Clear f
Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 127$
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Description:	The contents of register 'f' are cleared and the Z bit is set.

CLRW	Clear W
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W) 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

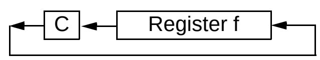
CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{TO}$ 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	`CLRWDT` instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF	Complement f
Syntax:	[*label*] COMF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	$(\bar{f})$ → (destination)
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

DECF	Decrement f
Syntax:	[*label*] DECF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

RLF — Rotate Left f through Carry

Syntax:	[*label*] RLF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	See description below
Status Affected:	C
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.



RETURN — Return from Subroutine

Syntax:	[*label*] RETURN
Operands:	None
Operation:	TOS → PC
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

RRF — Rotate Right f through Carry

Syntax:	[*label*] RRF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	See description below
Status Affected:	C
Description:	The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

SLEEP

Syntax:	[*label*] SLEEP
Operands:	None
Operation:	00h → WDT, 0 → WDT prescaler, 1 → $\overline{TO}$, 0 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped.

SUBLW — Subtract W from Literal

Syntax:	[*label*] SUBLW k
Operands:	0 ≤ k ≤ 255
Operation:	k - (W) → (W)
Status Affected:	C, DC, Z
Description:	The W register is subtracted (2's complement method) from the eight-bit literal 'k'. The result is placed in the W register.

SUBWF — Subtract W from f

Syntax:	[*label*] SUBWF f,d
Operands:	0 ≤ f ≤ 127 d ∈ [0,1]
Operation:	(f) - (W) → (destination)
Status Affected:	C, DC, Z
Description:	Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

15.2 DC Characteristics: PIC16F873/874/876/877-04 (Commercial, Industrial) PIC16F873/874/876/877-20 (Commercial, Industrial) PIC16LF873/874/876/877-04 (Commercial, Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in DC specification (Section 15.1)				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	Vss	—	0.15VDD	V	For entire VDD range
D030A			Vss	—	0.8V	V	4.5V ≤ VDD ≤ 5.5V
D031		with Schmitt Trigger buffer	Vss	—	0.2VDD	V	
D032		$\overline{MCLR}$, OSC1 (in RC mode)	VSS	—	0.2VDD	V	
D033		OSC1 (in XT, HS and LP)	VSS	—	0.3VDD	V	**(Note 1)**
		Ports RC3 and RC4		—			
D034		with Schmitt Trigger buffer	Vss	—	0.3VDD	V	For entire VDD range
D034A		with SMBus	-0.5	—	0.6	V	for VDD = 4.5 to 5.5V
	VIH	**Input High Voltage**					
		I/O ports		—			
D040		with TTL buffer	2.0	—	VDD	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	—	VDD	V	For entire VDD range
D041		with Schmitt Trigger buffer	0.8VDD	—	VDD	V	For entire VDD range
D042		$\overline{MCLR}$	0.8VDD	—	VDD	V	
D042A		OSC1 (XT, HS and LP)	0.7VDD	—	VDD	V	**(Note 1)**
D043		OSC1 (in RC mode)	0.9VDD	—	VDD	V	
		Ports RC3 and RC4					
D044		with Schmitt Trigger buffer	0.7VDD	—	VDD	V	For entire VDD range
D044A		with SMBus	1.4	—	5.5	V	for VDD = 4.5 to 5.5V
D070	IPURB	**PORTB Weak Pull-up Current**	50	250	400	μA	VDD = 5V, VPIN = VSS, -40°C TO +85°C
	IIL	**Input Leakage Current(2, 3)**					
D060		I/O ports	—	—	±1	μA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061		$\overline{MCLR}$, RA4/T0CKI	—	—	±5	μA	Vss ≤ VPIN ≤ VDD
D063		OSC1	—	—	±5	μA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16F87X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 15-6: EXTERNAL CLOCK TIMING

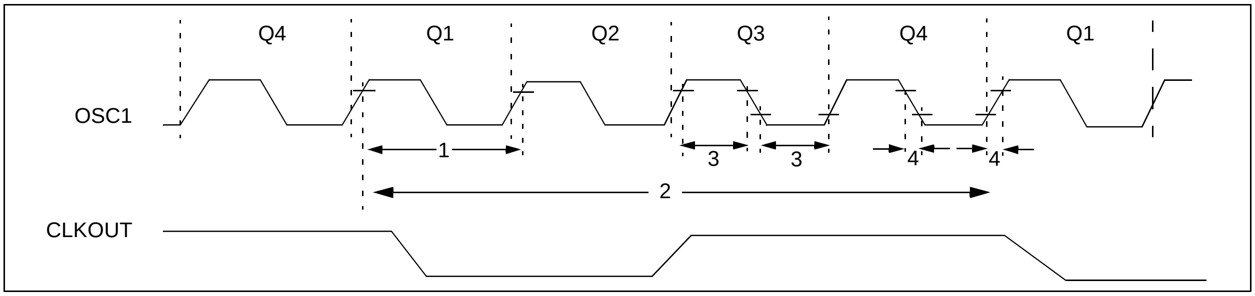


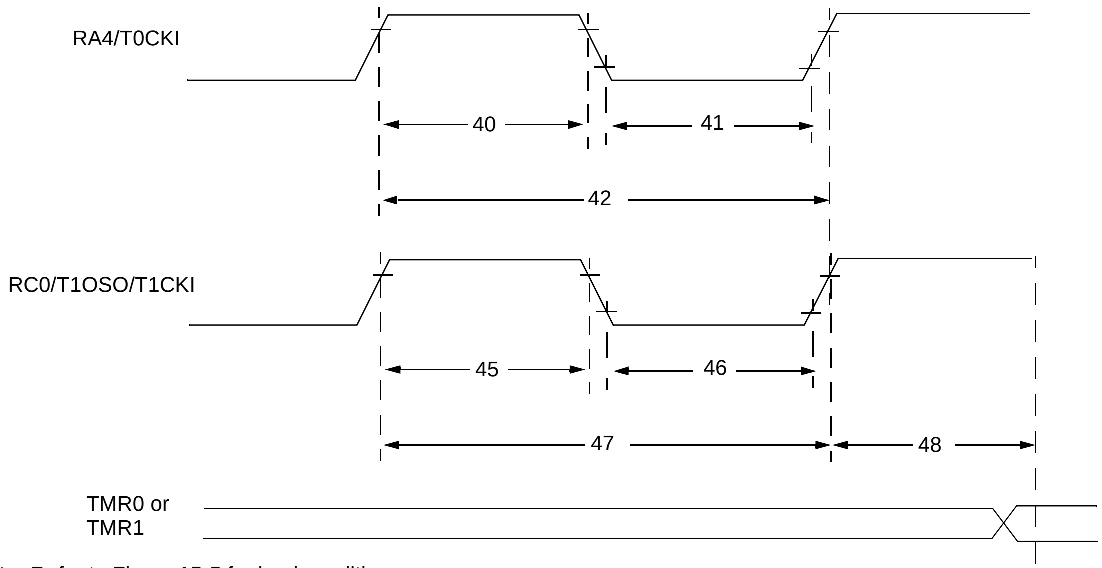
TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	FOSC	External CLKIN Frequency **(Note 1)**	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency **(Note 1)**	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	10	MHz	HS osc mode (-10)
			4	—	20	MHz	HS osc mode (-20)
			5	—	200	kHz	LP osc mode
1	TOSC	External CLKIN Period **(Note 1)**	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period **(Note 1)**	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	TCY	Instruction Cycle Time **(Note 1)**	200	TCY	DC	ns	TCY = 4/FOSC
3	TosL, TosH	External Clock in (OSC1) High or Low Time	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions, with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 15-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Note: Refer to Figure 15-5 for load conditions.

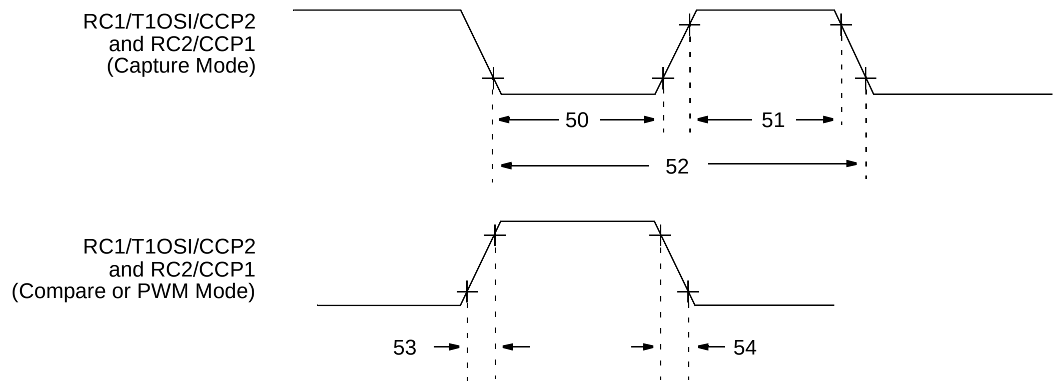
TABLE 15-4: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Symbol	Characteristic			Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
				With Prescaler	Greater of: 20 or $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (2, 4,..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	Standard(**F**)	15	—	—	ns	
				Extended(**LF**)	25	—	—	ns	
			Asynchronous	Standard(**F**)	30	—	—	ns	
				Extended(**LF**)	50	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	Standard(**F**)	15	—	—	ns	
				Extended(**LF**)	25	—	—	ns	
			Asynchronous	Standard(**F**)	30	—	—	ns	
				Extended(**LF**)	50	—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	Standard(**F**)	Greater of: 30 OR $\frac{T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 2, 4, 8)
				Extended(**LF**)	Greater of: 50 OR $\frac{T_{CY} + 40}{N}$				N = prescale value (1, 2, 4, 8)
			Asynchronous	Standard(**F**)	60	—	—	ns	
				Extended(**LF**)	100	—	—	ns	
	Ft1	Timer1 oscillator input frequency range (oscillator enabled by setting bit T1OSCEN)			DC	—	200	kHz	
48	TCKEZtmr1	Delay from external clock edge to timer increment			2TOSC	—	7TOSC	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-11: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)



Note: Refer to Figure 15-5 for load conditions.

TABLE 15-5: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard(**F**)	10	—	—	ns	
				Extended(**LF**)	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard(**F**)	10	—	—	ns	
				Extended(**LF**)	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 4 or 16)
53*	TccR	CCP1 and CCP2 output rise time		Standard(**F**)	—	10	25	ns	
				Extended(**LF**)	—	25	50	ns	
54*	TccF	CCP1 and CCP2 output fall time		Standard(**F**)	—	10	25	ns	
				Extended(**LF**)	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 15-12: PIC16F87X-04 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16F87X-10 (EXTENDED) PIC16F87X-20 (COMMERCIAL, INDUSTRIAL) PIC16LF87X-04 (COMMERCIAL, INDUSTRIAL)

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
A01	N_R	Resolution		—	—	10-bits	bit	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \le V_{AIN} \le V_{REF}$
A03	E_{IL}	Integral linearity error		—	—	< ± 1	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \le V_{AIN} \le V_{REF}$
A04	E_{DL}	Differential linearity error		—	—	< ± 1	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \le V_{AIN} \le V_{REF}$
A06	E_{OFF}	Offset error		—	—	< ± 2	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \le V_{AIN} \le V_{REF}$
A07	E_{GN}	Gain error		—	—	< ± 1	LSb	$V_{REF} = V_{DD} = 5.12V$, $V_{SS} \le V_{AIN} \le V_{REF}$
A10	—	Monotonicity[3]		—	guaranteed	—	—	$V_{SS} \le V_{AIN} \le V_{REF}$
A20	V_{REF}	Reference voltage (V_{REF+} - V_{REF-})		2.0	—	V_{DD} + 0.3	V	Absolute minimum electrical spec. To ensure 10-bit accuracy.
A21	V_{REF+}	Reference voltage High		AV_{DD} - 2.5V		AV_{DD} + 0.3V	V	
A22	V_{REF-}	Reference voltage low		AV_{SS} - 0.3V		V_{REF+} - 2.0V	V	
A25	V_{AIN}	Analog input voltage		V_{SS} - 0.3 V	—	V_{REF} + 0.3 V	V	
A30	Z_{AIN}	Recommended impedance of analog voltage source		—	—	10.0	kΩ	
A40	I_{AD}	A/D conversion current (V_{DD})	Standard	—	220	—	μA	Average current consumption when A/D is on **(Note 1)**
			Extended	—	90	—	μA	
A50	I_{REF}	V_{REF} input current **(Note 2)**		10	—	1000	μA	During V_{AIN} acquisition. Based on differential of V_{HOLD} to V_{AIN} to charge C_{HOLD}, see Section 11.1.
				—	—	10	μA	During A/D Conversion cycle

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

2: V_{REF} current is from RA3 pin or V_{DD} pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the input voltage, and has no missing codes.

FIGURE 16-5: TYPICAL IDD vs. FOSC OVER VDD (LP MODE)

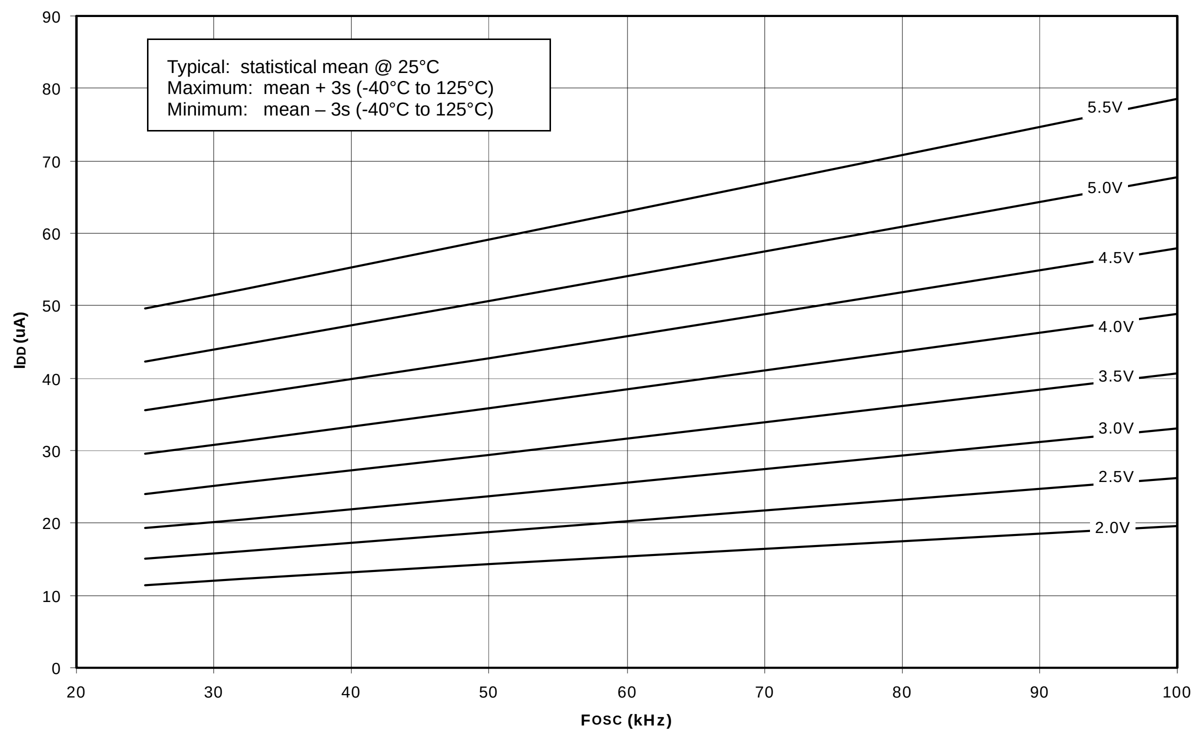


FIGURE 16-6: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE)

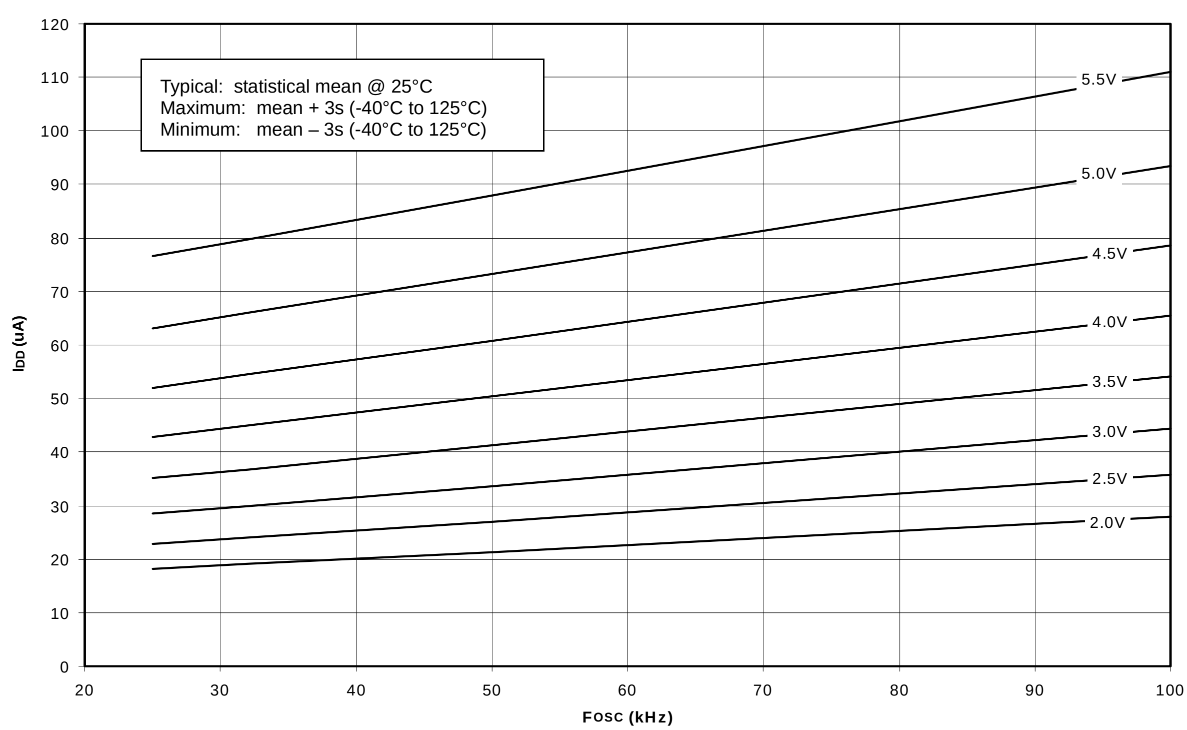


FIGURE 16-21: MINIMUM AND MAXIMUM V_{IN} vs. V_{DD} (ST INPUT, -40°C TO 125°C)

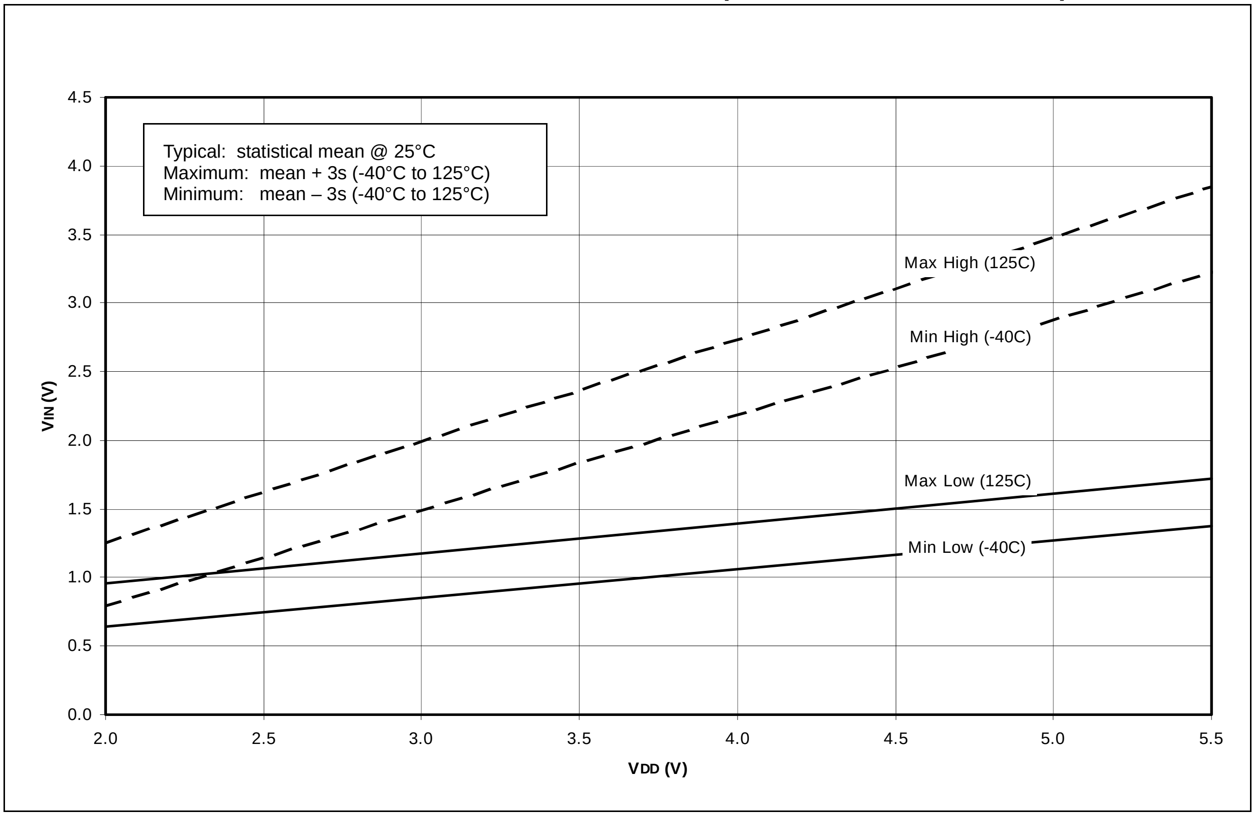
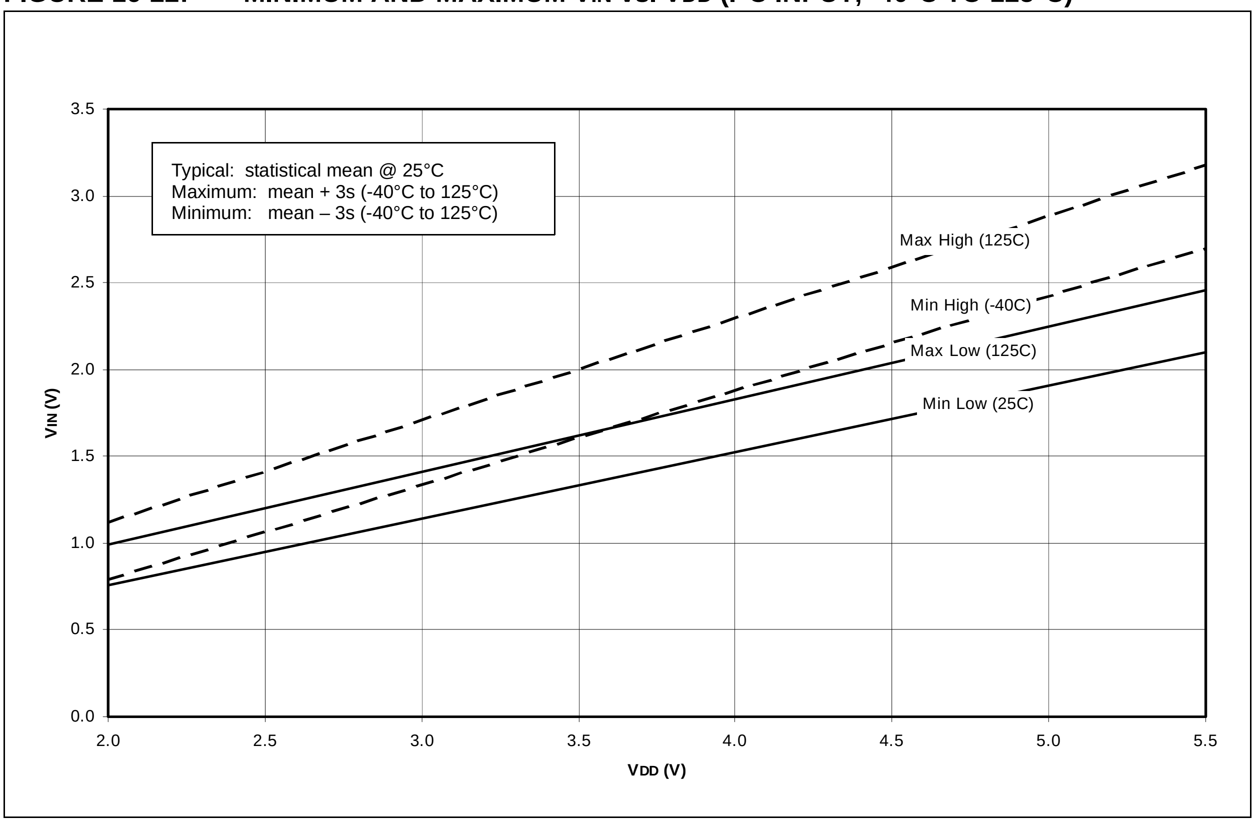
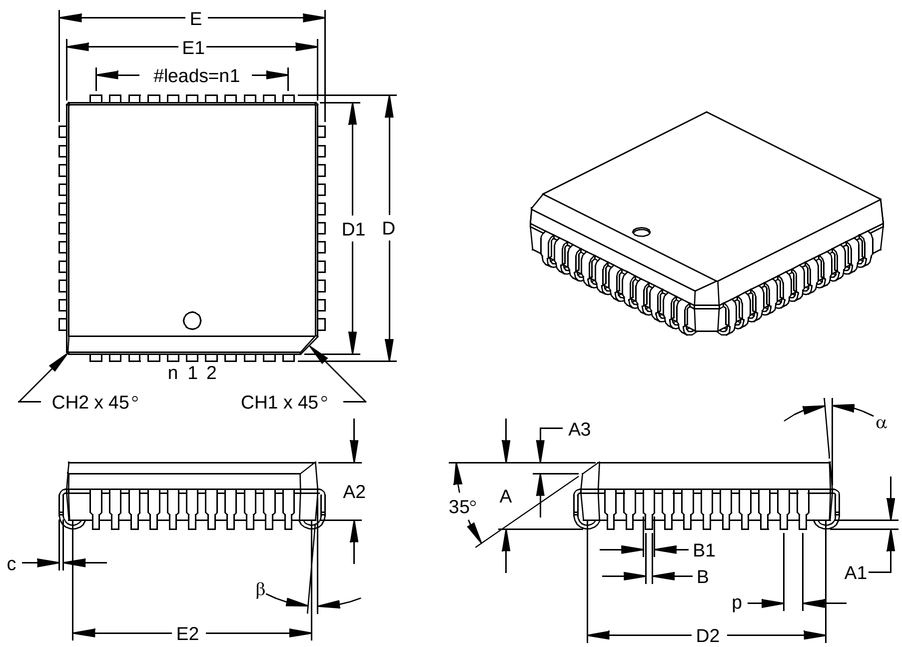


FIGURE 16-22: MINIMUM AND MAXIMUM V_{IN} vs. V_{DD} (I^2C INPUT, -40°C TO 125°C)



44-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES*			MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.050			1.27	
Pins per Side	n1		11			11	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.685	.690	.695	17.40	17.53	17.65
Overall Length	D	.685	.690	.695	17.40	17.53	17.65
Molded Package Width	E1	.650	.653	.656	16.51	16.59	16.66
Molded Package Length	D1	.650	.653	.656	16.51	16.59	16.66
Footprint Width	E2	.590	.620	.630	14.99	15.75	16.00
Footprint Length	D2	.590	.620	.630	14.99	15.75	16.00
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-048

D

E

F

G

I

PIC16F87X PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC16F87X(1), PIC16F87XT(2); VDD range 4.0V to 5.5V PIC16LF87X(1), PIC16LF87XT(2); VDD range 2.0V to 5.5V
Frequency Range	04 = 4 MHz 10 = 10 MHz 20 = 20 MHz
Temperature Range	blank = 0°C to +70°C (Commercial) I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package	PQ = MQFP (Metric PQFP) PT = TQFP (Thin Quad Flatpack) SO = SOIC SP = Skinny plastic DIP P = PDIP L = PLCC

Examples:

a) PIC16F877 - 20/P 301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301.

b) PIC16LF876 - 04I/SO = Industrial temp., SOIC package, 200 kHz, Extended VDD limits.

c) PIC16F877 - 10E/P = Extended temp., PDIP package, 10MHz, normal VDD limits.

Note 1: F = CMOS FLASH
LF = Low Power CMOS FLASH
2: T = in tape and reel - SOIC, PLCC, MQFP, TQFP packages only.

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets
Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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